



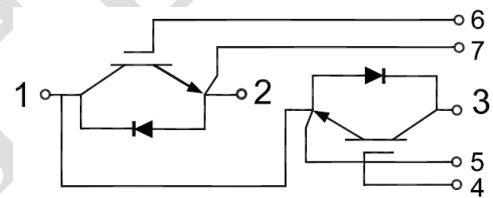
# GT300HF170T2VH

## IGBT Module

Preliminary Data

### Features:

- Field Stop Trench Gate IGBT
- Short Circuit Rated > 10 $\mu$ s
- Low Saturation Voltage
- Low Switching Loss
- 100% RBSOA Tested (2 $\times$ I<sub>c</sub>)
- Low Stray Inductance
- Lead Free, Compliant with RoHS Requirement



### Applications:

- High Power Converters
- Wind Turbines
- Motor Drives
- UPS Systems

### IGBT, Inverter

#### Maximum Rated Values of IGBT (T<sub>c</sub>=25 $^{\circ}$ C unless otherwise specified)

V <sub>CES</sub>	Collector-Emitter Blocking Voltage		1700	V
V <sub>GES</sub>	Gate-Emitter Voltage		$\pm$ 20	V
I <sub>c</sub>	Continuous Collector Current	T <sub>c</sub> =100 $^{\circ}$ C	300	A
		T <sub>c</sub> =25 $^{\circ}$ C	570	A
I <sub>CM</sub>	Peak Collector Current Repetitive	T <sub>j</sub> =175 $^{\circ}$ C	600	A
t <sub>SC</sub>	Short Circuit Withstand Time		>10	$\mu$ s
P <sub>D</sub>	Maximum Power Dissipation (IGBT)	T <sub>c</sub> =25 $^{\circ}$ C T <sub>Jmax</sub> =175 $^{\circ}$ C	2055	W



## Electrical Characteristics of IGBT ( $T_C=25^\circ\text{C}$ unless otherwise specified)

### Static Characteristics

Symbol	Description	Conditions	Min	Typ	Max	Unit
$V_{GE(th)}$	Gate-Emitter Threshold Voltage	$I_C=12\text{mA}$ , $V_{CE}=V_{GE}$	4.5	5.5	6.5	V
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$I_C=300\text{A}$ , $V_{GE}=15\text{V}$	$T_J=25^\circ\text{C}$	1.80		V
			$T_J=125^\circ\text{C}$	2.20		V
			$T_J=150^\circ\text{C}$	2.30		
$I_{CES}$	Collector-Emitter Leakage Current	$V_{GE}=0\text{V}$ , $V_{CE}=V_{CES}$ , $T_J=25^\circ\text{C}$			1	mA
$I_{GES}$	Gate-Emitter Leakage Current	$V_{GE}=\pm 20\text{V}$ , $V_{CE}=0\text{V}$ , $T_J=25^\circ\text{C}$			300	nA
$C_{ies}$	Input Capacitance	$V_{CE}=25\text{V}$ , $V_{GE}=0\text{V}$ , $f=1\text{MHz}$		31.23		nF
$C_{oes}$	Output Capacitance			1.86		nF
$C_{res}$	Reveres Transfer Capacitance			0.36		nF

### Switching Characteristics

$t_{d(on)}$	Turn-on Delay Time	$V_{CC}=900\text{V}$ , $I_C=300\text{A}$ , $R_{Gon}=2\ \Omega$ , $V_{GE}=\pm 15\text{V}$ , Inductive Load	$T_J=25^\circ\text{C}$	0.32		$\mu\text{s}$
			$T_J=125^\circ\text{C}$	0.33		
			$T_J=150^\circ\text{C}$	0.33		
$t_r$	Rise Time		$T_J=25^\circ\text{C}$	0.12		$\mu\text{s}$
			$T_J=125^\circ\text{C}$	0.14		
			$T_J=150^\circ\text{C}$	0.14		
$t_{d(off)}$	Turn-off Delay Time		$T_J=25^\circ\text{C}$	0.27		$\mu\text{s}$
			$T_J=125^\circ\text{C}$	0.30		
			$T_J=150^\circ\text{C}$	0.30		
$t_f$	Fall Time	$T_J=25^\circ\text{C}$	0.17		$\mu\text{s}$	
		$T_J=125^\circ\text{C}$	0.29			
		$T_J=150^\circ\text{C}$	0.32			
$E_{on}$	Turn-on Switching Loss	$V_{CC}=900\text{V}$ , $I_C=300\text{A}$ , $R_{Gon}=2\ \Omega$ , $V_{GE}=\pm 15\text{V}$ , Inductive Load $di/dt=1550\text{A}/\mu\text{s}$ ( $T_J=150^\circ\text{C}$ )	$T_J=25^\circ\text{C}$	71.5		mJ
		$T_J=125^\circ\text{C}$	103			
		$T_J=150^\circ\text{C}$	113			



E <sub>off</sub>	Turn-off Switching Loss	V <sub>CC</sub> =900V, I <sub>C</sub> =300A, R <sub>Goff</sub> =2 Ω, V <sub>GE</sub> = ±15V, Inductive Load du/dt =2850V/μs(T <sub>J</sub> =150°C)	T <sub>J</sub> =25°C	77.5	mJ
			T <sub>J</sub> =125°C	104.5	
			T <sub>J</sub> =150°C	111.5	
Q <sub>g</sub>	Total Gate Charge	V <sub>GE</sub> =-15V...+15V	T <sub>J</sub> =25°C	1.53	μC
R <sub>BSOA</sub>	I <sub>C</sub> =600A, V <sub>CC</sub> =1620V, V <sub>p</sub> =1700V, R <sub>Goff</sub> =2Ω, V <sub>GE</sub> =+15V to 0V, T <sub>J</sub> =150°C			Trapezoid	
SCSOA	V <sub>CC</sub> =900V, V <sub>GE</sub> =15V, T <sub>J</sub> =150°C			10	μs
R <sub>θJC</sub>	IGBT Thermal Resistance: Junction-To-Case (per leg)			0.073	°C/W

### Diode, Inverter

#### Maximum Rated Values of Diode (T<sub>C</sub>=25°C unless otherwise specified)

V <sub>RRM</sub>	Repetitive Peak Reverse Voltage	1700	V
I <sub>F</sub>	Diode Continuous Forward Current	300	A
I <sub>FM</sub>	Peak FWD Current Repetitive	600	A

#### Electrical Characteristics of Diode (T<sub>C</sub>=25°C unless otherwise specified)

V <sub>FM</sub>	Forward Voltage	I <sub>F</sub> =300 A	T <sub>J</sub> =25°C	2.80	V
			T <sub>J</sub> =125°C	3.00	
			T <sub>J</sub> =150°C	3.00	
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> =300A, -di <sub>F</sub> /dt=1950A/μs(T <sub>J</sub> =150°C), V <sub>R</sub> =900V, V <sub>GE</sub> = -15V	T <sub>J</sub> =25°C	0.33	μs
			T <sub>J</sub> =125°C	0.47	
			T <sub>J</sub> =150°C	0.52	
I <sub>rr</sub>	Peak Reverse Recovery Current	I <sub>F</sub> =300A, -di <sub>F</sub> /dt=1950A/μs(T <sub>J</sub> =150°C), V <sub>R</sub> =900V, V <sub>GE</sub> = -15V	T <sub>J</sub> =25°C	84.5	A
			T <sub>J</sub> =125°C	119	
			T <sub>J</sub> =150°C	125	
Q <sub>rr</sub>	Reverse Recovery Charge	I <sub>F</sub> =300A, -di <sub>F</sub> /dt=1950A/μs(T <sub>J</sub> =150°C), V <sub>R</sub> =900V, V <sub>GE</sub> = -15V	T <sub>J</sub> =25°C	19	μC
			T <sub>J</sub> =125°C	45.5	
			T <sub>J</sub> =150°C	55.5	



E <sub>rec</sub>	Reverse Recovery Energy	I <sub>F</sub> =300A, -di <sub>F</sub> /dt=1950A/μs(T <sub>J</sub> =150°C), V <sub>R</sub> =900V, V <sub>GE</sub> = -15V	T <sub>J</sub> =25°C		11	mJ
			T <sub>J</sub> =125°C		24.5	
			T <sub>J</sub> =150°C		30.5	
R <sub>θJC</sub>	Diode Thermal Resistance: Junction-To-Case (per leg)				0.076	°C/W

## Module

Symbol	Description		Min	Typ	Max	Unit
V <sub>iso</sub>	Isolation Voltage (All Terminals Shorted)	RMS, f=50Hz, 1minute	2500			V
T <sub>J</sub>	Maximum Junction Temperature				175	°C
T <sub>JOP</sub>	Maximum Operating Junction Temperature Range		-40		+150	°C
T <sub>stg</sub>	Storage Temperature		-40		+125	°C
CTI	Comparative Tracking Index		200			
R <sub>θCS</sub>	Case-To-Sink Thermally (Conductive Grease Applied)			0.03		°C/W
M	Power Terminals Screw:M6		3.0		5.0	N·m
M	Mounting Screw:M6		4.0		6.0	N·m
G	Weight			300		g

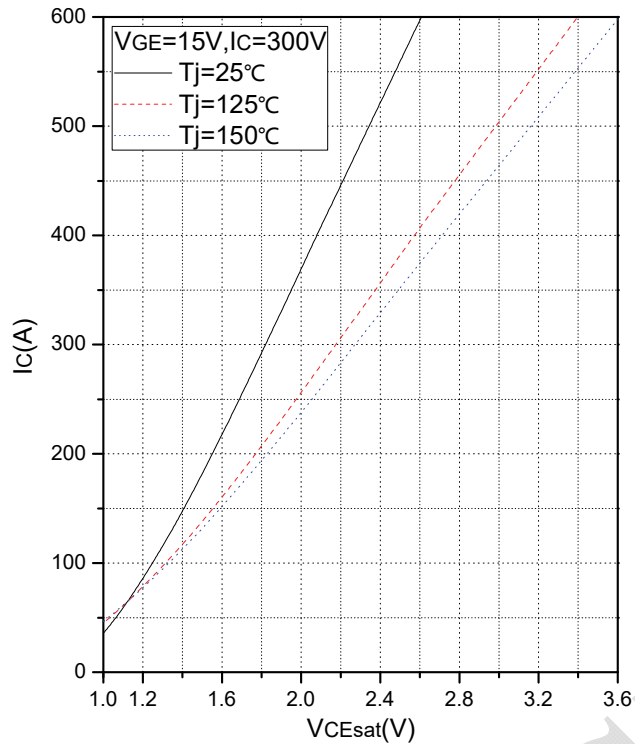


Fig.1 Typical Saturation Voltage Characteristics

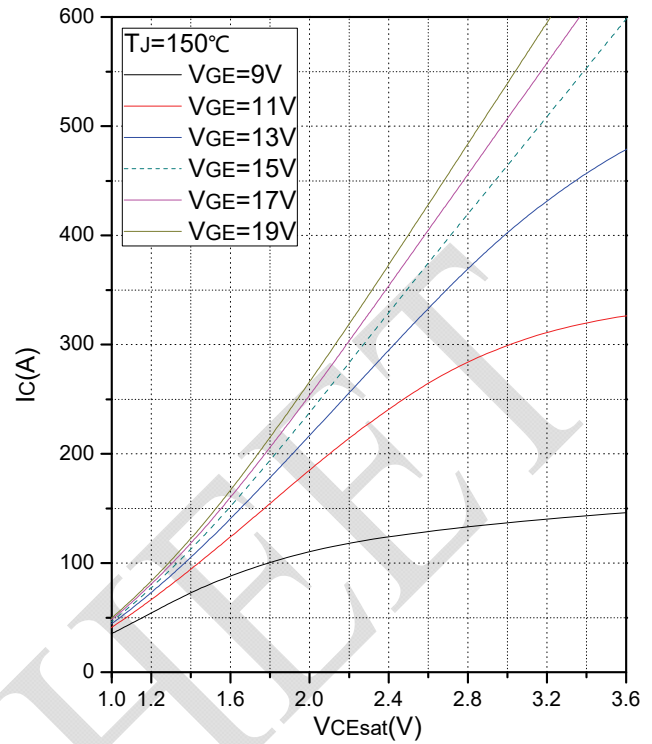


Fig.2 Typical Output Characteristics

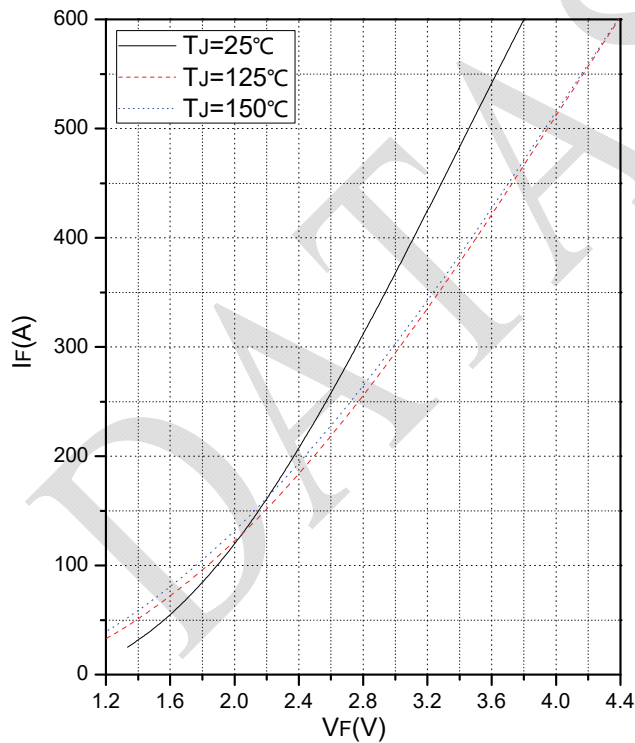


Fig.3 Forward Characteristics of Inverter Diode

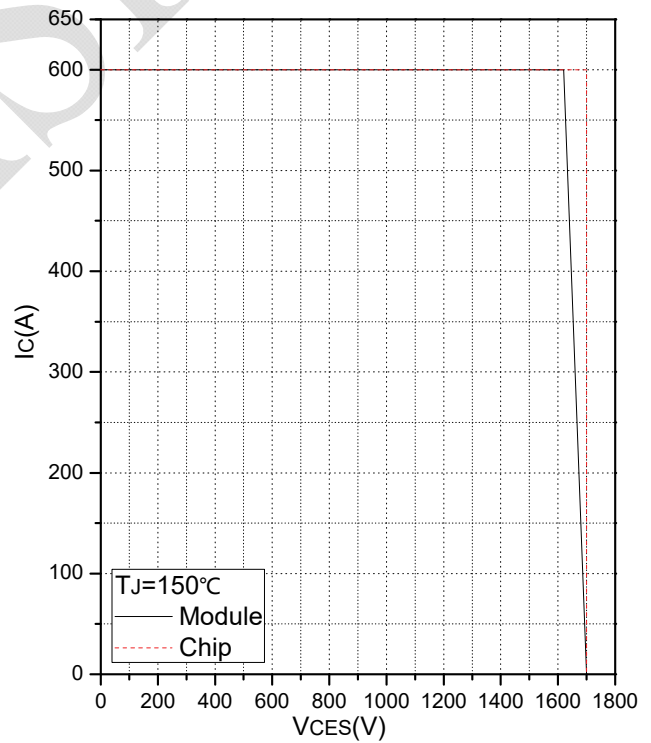


Fig.4 Reverse Bias Safe Operation Area (RBSOA)

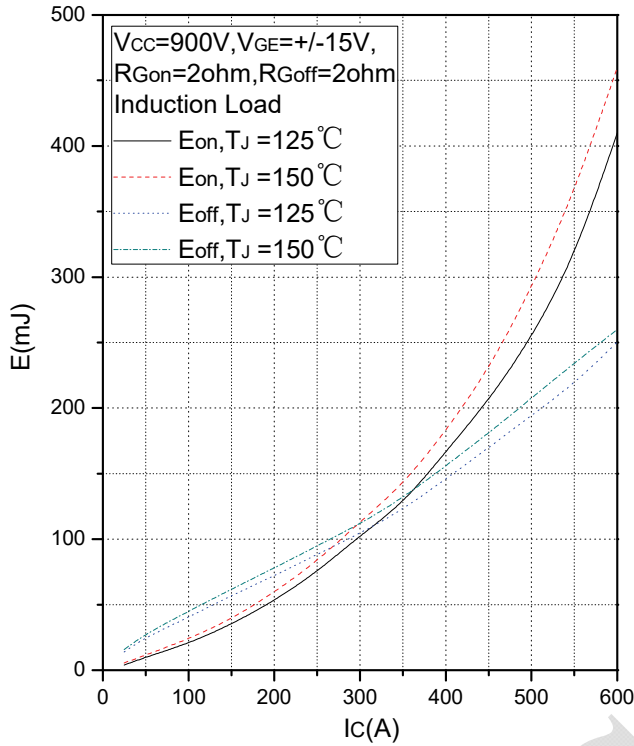


Fig.5 Typical Switching Loss vs. Collector Current

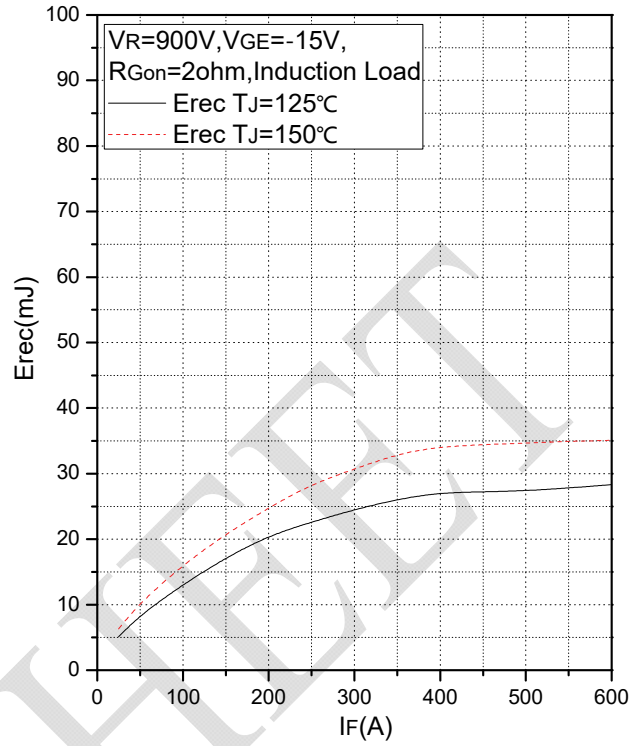


Fig.6 Typical Switching Loss vs. Forward Current

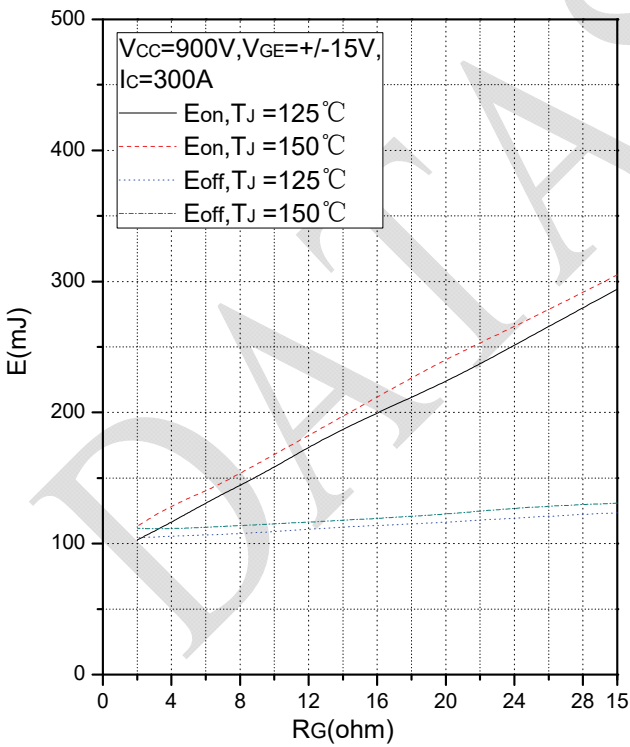


Fig.7 Typical Switching Loss vs. Gate Resistance

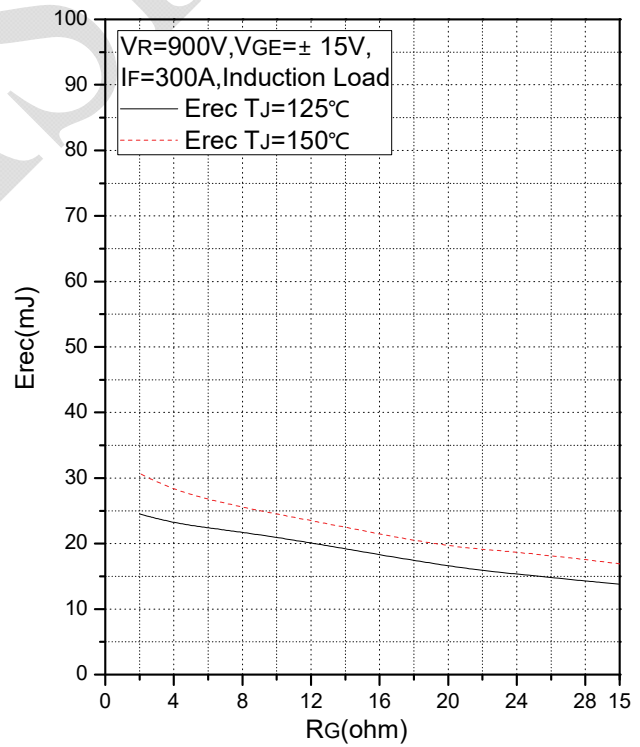


Fig.8 Typical Switching Loss vs. Gate Resistance

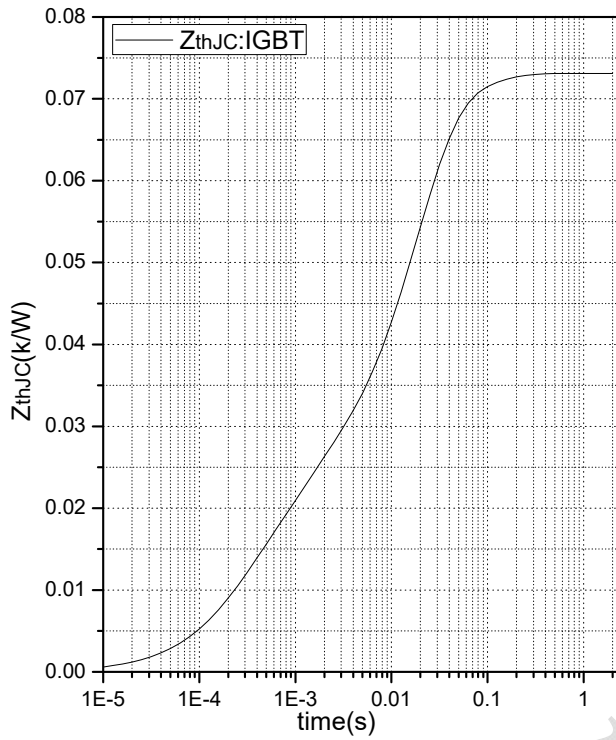


Fig.9 Transient Thermal Impedance ( IGBT)

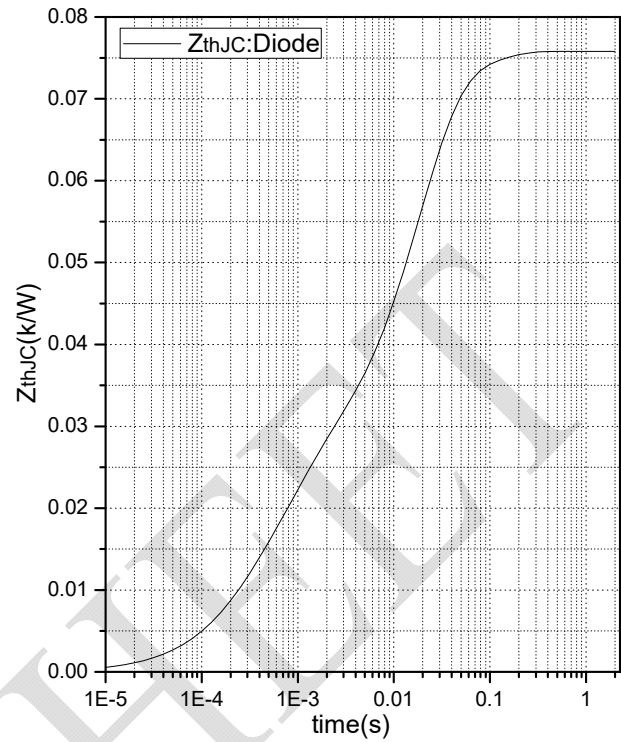
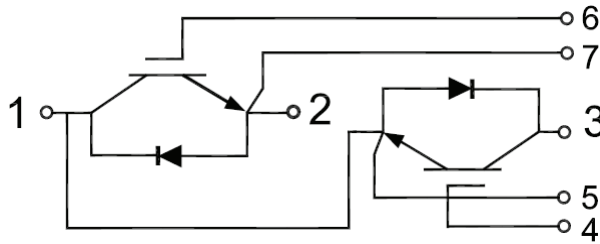


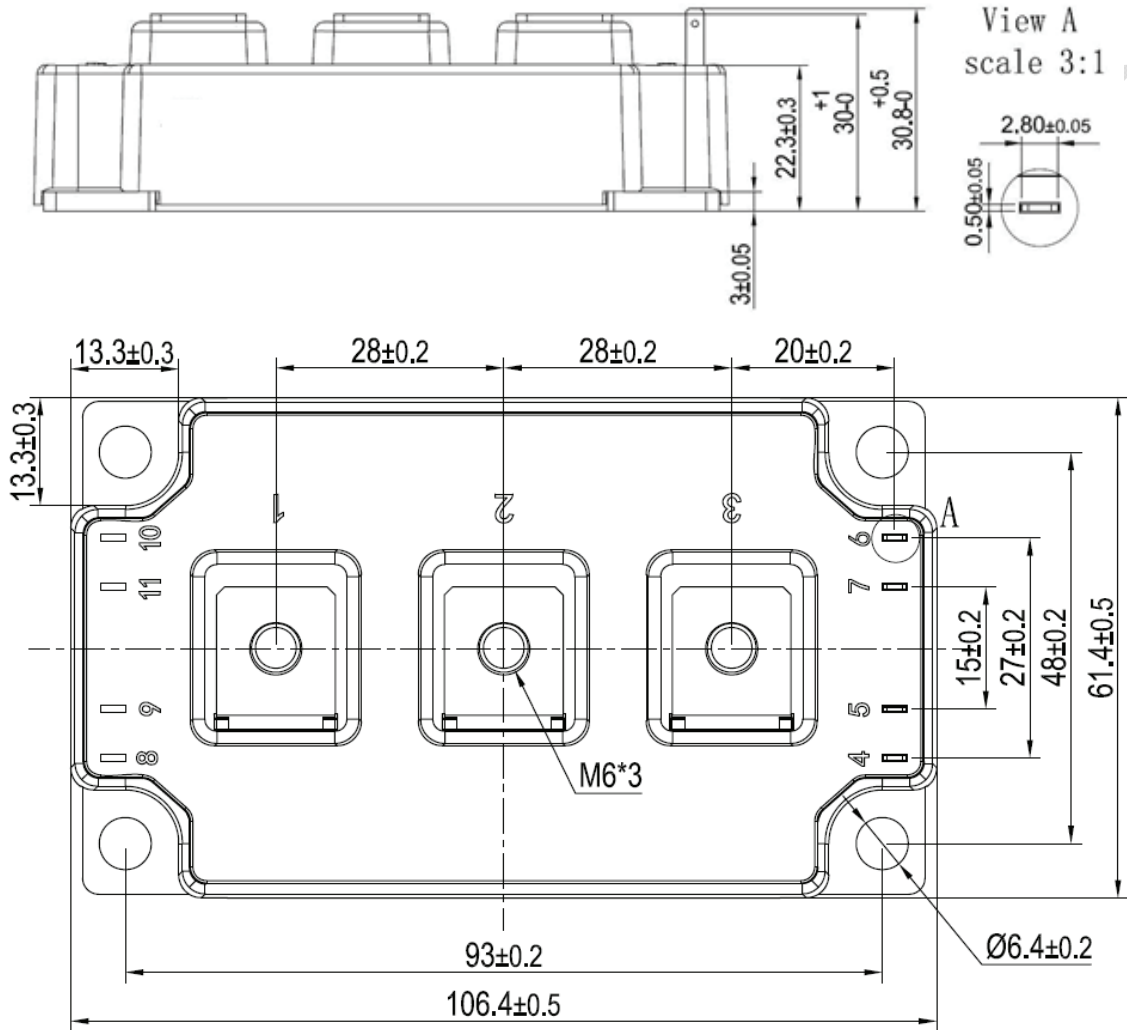
Fig.10 Transient Thermal Impedance (Diode)



### Internal Circuit



### Package Outline (Unit: mm):







## Revision History

Date	Revision	Notes
11/20/2020	01	Initial Release

### Announcement

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